

Supplier Name: Texas Instruments Inc. (DUNS# 00-732-1904)
 Contact Info: ti.com/support
 Form/Declaration Type: Distribute - RoHS and IEC 62474 DB
 Created on: 06/12/2022

Details for "TPS7B6950QDBVRQ1"

Current Product Information

TI part number	Lead finish/Ball material	MSL rating/peak reflow	Assembly site	Package Pins	Package body size (mm)	Total device mass (mg)*
TPS7B6950QDBVRQ1	SN	Level-2-260C-1 YEAR	Ext-Mfg	DBV 5	2.9x1.6x1.45	18.4

*Total Device Mass

The summary mass is a rounded value and will be within approximately +/- 10% of the detailed mass value.

Environmental Ratings Information

RoHS	REACH	Green	IEC 62474 DB
Yes	Yes	Yes	Yes

Component Information

Component	Substance	CAS Number	Amount (mg)	Homogeneous Material Level		Component Level	
				Percentage %	ppm	Percentage %	ppm
Bond Wire							
Copper and Its Alloys	Copper	7440-50-8	0.029162	97.203427	972034	0.158067	1581
Precious Metals	Palladium	7440-05-3	0.000839	2.796573	27966	0.004548	45
Sub-Total			0.030001	100	1000000	0.162614	1626
Die Attach Adhesive							
Precious Metals	Silver	7440-22-4	0.157832	80	800000	0.855495	8555
Thermoplastics	Epoxy	85954-11-6	0.039458	20	200000	0.213874	2139
Sub-Total			0.19729	100	1000000	1.069369	10694
Lead Frame							
Copper and Its Alloys	Copper	7440-50-8	6.041349	97.437514	974375	32.745864	327459
Copper and Its Alloys	Iron	7439-89-6	0.145705	2.349994	23500	0.789763	7898
Copper and Its Alloys	Phosphorus	7723-14-0	0.005115	0.082497	825	0.027725	277
Other Nonferrous Metals and Alloys	Lead	7439-92-1	0.00031	0.005	50	0.00168	17
Zinc and Its Alloys	Zinc	7440-66-6	0.00775	0.124995	1250	0.042007	420
Sub-Total			6.200229	100	1000000	33.60704	336070
Lead Frame Plating							
Other Nonferrous Metals and Alloys	Tin	7440-31-5	0.012	100	1000000	0.065043	650
Sub-Total			0.012	100	1000000	0.065043	650
Mold Compound							
Other Inorganic Materials	Fused Silica	60676-86-0	9.693773	83.699998	837000	52.543062	525431
Other Plastics and Rubber	Carbon Black	1333-86-4	0.034745	0.300003	3000	0.188328	1883
Thermoplastics	Epoxy	85954-11-6	1.853051	16	160000	10.044074	100441
Sub-Total			11.581569	100	1000000	62.775464	627755
Semiconductor Device							
Ceramics / Glass	Doped Silicon	7440-21-3	0.428108	100	1000000	2.32047	23205
Sub-Total			0.428108	100	1000000	2.32047	23205
Total			18.449197			100	1000000

Important Note

The ppm calculations are at the **homogeneous material** level and are maximum concentration values. The ppm displayed represents the **homogeneous material** with the highest ppm for that substance. The amount (mg) calculations represent the maximum total amount of each substance within the component.

The ppm calculations are at the **component** level and are average concentration values. The amount (mg) calculations represent the average total amount of each substance within the **component**.

[See Glossary of Terms for more details.](#)

Important Part Information

There is a remote possibility the Customer Part Number (CPN) your company uses could reference more than one TI part number. This is due to two or more users (EMSI or subcontractors) using the same CPN for different TI part numbers. If this occurs, please check your Customer Part Number and cross reference it with the TI part number seen on this page.

Product Content Methodology

[For an explanation of the methods used to determine material weights, See Product Content Methodology](#)

Material Declaration Certificate for Semiconductor IC Packaged Products

TI certifies that the material content information provided by TI is representative and accurate to the best of their knowledge based on material information provided by its suppliers and their combination into finished IC packaged products. TI semiconductor products designated to be "Pb-free", "Green" or "RoHS Exempt" fully meets the latest EU RoHS Directive requirements along with other legislation as seen in the former JIG-101 list that has been transferred to the IEC 62474 database.

Important Information/Disclaimer

TI bases its material content information on information provided by third-party suppliers and has taken, and continues to take, reasonably diligent steps to provide any required or available information. TI may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers may consider certain information to be proprietary, and thus certain information may not be available for release by TI. The material content information is provided by TI "as is."

[For additional information, please contact TI customer support.](#)

Signature: [\(click here for a fuller statement with a signed certificate\)](#)

Name/Title: Hubie Payne, Vice President, Worldwide SC Quality
 For further environmental statements, please go to www.ti.com/eoinfo
 Created on: 06/12/2022

RoHS: Means TI semiconductor products that are compliant with the current RoHS requirement that the maximum concentration values of the ten substances listed in RoHS Annex II do not exceed 0.1 % by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI semiconductor products labeled as "RoHS Compliant" are suitable for use in specified lead-free processes. TI may also reference these types of semiconductor products as "Pb-Free." These TI semiconductor products are also fully compliant with GADSL and the IEC 62474 database for electronic requirements.

RoHS Exempt: Means TI semiconductor products that contain lead (Pb) above the RoHS Annex II threshold, but that fall within one of the specific RoHS exemptions noted above or documented in <http://www.ti.com/lit/pdf/szzq088>

Green: Means the content of Chlorine (Cl) and Bromine (Br)-based flame retardants meet JS709B low halogen requirements of <=1 000ppm threshold; Antimony trioxide (Sb2O3) contained in halogen based flame retardant materials meets the <=1 000ppm threshold requirement; and Beryllium Oxide (BeO) is <=1000ppm.